



REV.	DESCRIPTION	ECN NO.	NAME	DATE

PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

Part No	PIN	DIMA	DIMB	DIMC
WF-1A150A2P	2	1.5	3.6	4.5
WF-1A150A3P	3	3	5.1	6
WF-1A150A4P	4	4.5	6.6	7.5
WF-1A150A5P	5	6	8.1	9
WF-1A150A6P	6	7.5	9.6	10.5
WF-1A150A7P	7	9	11.1	12
WF-1A150A8P	8	10.5	12.6	13.5
WF-1A150A9P	9	12	14.1	15
WF-1A150A10P	10	13.5	15.6	16.5
WF-1A150A11P	11	15	17.1	18
WF-1A150A12P	12	16.5	18.6	19.5
WF-1A150A13P	13	18	20.1	21
WF-1A150A14P	14	19.5	21.6	22.5
WF-1A150A15P	15	21	23.1	24
WF-1A150A16P	16	22.5	24.6	25.5

ROHS管理规定:

1. 禁止使用含有ROHS指令所限制的物质。
2. 对应的SGS或ITS出具的ICP-AES数据, 不可测定物质的成分表, 有效期一年。

技术指标:

1. 塑件表面应光洁、无毛刺、明显收缩、缺陷、裂纹等现象;
2. 温度范围: $-25^{\circ}\text{C} \sim 85^{\circ}\text{C}$;
3. 额定电压: 250V, AC, DC(等效);
4. 接触电阻: $\leq 0.03\Omega$;
5. 绝缘电阻: $\geq 1000\text{M}\Omega$;
6. 耐压: 1000V, AC/minute.

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	附注

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD			
DIM.	TOL.	TITLE: WAFER 1.5mm H3.7mm 180°DIP			
X		DWG. NO.: WF-1A150ANP		DRAWN: MAX	
X.X	± 0.30	PART NO.: WF-1A150ANP		CHECKED: ELLA	
X.XX	± 0.25	UNIT: mm		APPROVED: WILL	
X.XXX	± 0.15	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn
GENERAL ANGLE:	$\pm 3^{\circ}$				

BXCONN[®]



PCB寸法
PCB Layout